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Part Number: [0737700200](#)
Status: **Active**
Overview: [HDM Backplane Connector System](#)
Description: HDM Board-to-Board Stacking Header, High Rise Vertical, SMC, Closed End Option, 72 Circuits, Stack Height 6.05mm

Documents:

[3D Model](#) [Packaging Specification PK-70873-0875 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Product Specification PS-73780-999-001 \(PDF\)](#)

Agency Certification

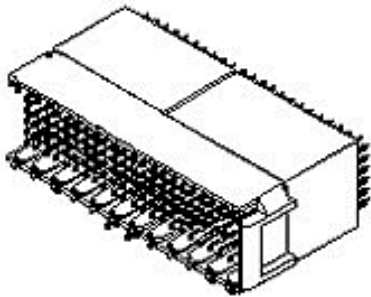
CSA LR19980
UL E29179

General

Product Family Backplane Connectors
Series [73770](#)
Application Backplane, Mezzanine
Component Type PCB Header
Overview [HDM Backplane Connector System](#)
Product Name HDM
UPC 800754828932

Physical

Circuits (Loaded) 72
Circuits (maximum) 72
Color - Resin Black
Durability (mating cycles max) 200
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Phosphor Bronze
Material - Plating Mating Gold
Material - Plating Termination Tin-Lead
Material - Resin High Temperature Thermoplastic
Net Weight 6.606/g
Number of Columns 12
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length 3.50mm
PCB Locator No
PCB Retention None
PCB Thickness - Recommended 1.40mm
Packaging Type Tube
Pitch - Mating Interface 2.00mm
Pitch - Termination Interface 2.00mm
Plating min - Mating 0.762µm
Plating min - Termination 0.381µm
Polarized to PCB No
Stackable Yes
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -55° to +105°C
Termination Interface: Style Through Hole - Compliant Pin



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

China RoHS

REACH SVHC

Not Contained Per -
ED/71/2019 (16 July
2019)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS Green Image
ELV Not Relevant
RoHS Phthalates Not Contained

Search Parts in this Series

[73770](#) Series

Mates With

[73632](#) HDM+ Board-to-Board Daughtercard
Receptacle. [73780](#) HDM Board-to-Board
Daughtercard Receptacle

Application Tooling | FAQ

*Tooling specifications and manuals are
found by selecting the products below.
Crimp Height Specifications are then
contained in the Application Tooling
Specification document.*

Global

Description	Product #
Extraction Tool	621001000
Backplane Insertion	621001400
Signal Contact Tool	
Backplane Signal	622008502
Insertion Module	
Press-In Tool for	
2.00mm Pitch HDM*	
Board-to-Board	
Backplane Header	

Electrical

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	72
Voltage - Maximum	250V AC

Solder Process Data

Lead-freeProcess Capability	N/A
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Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0875
Product Specification	PS-73780-999-001
Sales Drawing	SD-73770-001

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